L Number	Hits	Search Text	DB	Time stamp
1	2856	((((((((((((((conduct$3 copper) near5 (foil sheet layer)) and (etch$3 pattern$4)) and (via trench hole recess)) and (insulat$3 dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu aluminum Al)) and wir$3) and resin) and circuit) and (cover$3 encapsulat$3)) and ((etch$3 pattern$4) near10 (copper Cu conduct$3))) and wir$3) and (die bond$3)	USPAT; US-PGPUB	2003/04/29 18:26
2	5	((((((((((((((conduct$3 copper) near5 (foil sheet layer)) and (etch$3 pattern$4)) and (via trench hole recess)) and (insulat$3 dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu aluminum Al)) and wir$3) and resin) and circuit) and (cover$3 encapsulat$3)) and ((etch$3 pattern$4) near10 (copper Cu conduct$3))) and wir$3) and (die bond$3)	EPO; JPO; DERWENT; IBM_TDB	2003/04/29 18:27
3	5	((((((((((((((conduct$3 copper) near5 (foil sheet layer plate)) and (etch$3 pattern$4)) and (via trench hole recess)) and (insulat$3 dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu aluminum Al)) and wir$3) and resin) and circuit) and (cover$3 encapsulat$3)) and ((etch$3 pattern$4) near10 (copper Cu conduct$3))) and wir$3) and (die bond$3)	EPO; JPO; DERWENT; IBM_TDB	2003/04/29 18:28
4	2908	((((((((((((((conduct$3 copper) near5 (foil sheet layer plate)) and (etch$3 pattern$4)) and (via trench hole recess)) and (insulat$3 dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu aluminum Al)) and wir$3) and resin) and circuit) and (cover$3 encapsulat$3)) and ((etch$3 pattern$4) near10 (copper Cu conduct$3))) and wir$3) and (die bond$3)	USPAT; US-PGPUB	2003/04/29 18:29
5	52	(((((((((((((((conduct$3 copper) near5 (foil sheet layer plate)) and (etch$3 pattern$4)) and (via trench hole recess)) and (insulat$3 dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu aluminum Al)) and wir$3) and resin) and circuit) and (cover$3 encapsulat$3)) and ((etch$3 pattern$4) near10 (copper Cu conduct$3))) and wir$3) and (die bond$3)) not (((((((((((((((conduct$3 copper) near5 (foil sheet layer)) and (etch$3 pattern$4)) and (via trench hole recess)) and (insulat$3 dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu aluminum Al)) and wir$3) and resin) and circuit) and (cover$3 encapsulat$3)) and ((etch$3 pattern$4) near10 (copper Cu conduct$3))) and wir$3) and (die bond$3))	USPAT; US-PGPUB	2003/04/29 18:30
–	12192	conduct$3 near5 foil	USPAT; US-PGPUB	2003/02/11 15:12
–	4707	(conduct$3 near5 foil) and resin	USPAT; US-PGPUB	2003/02/11 12:50
–	3142	((conduct$3 near5 foil) and resin) and (pattern$5 etch$3)	USPAT; US-PGPUB	2003/02/11 12:51
–	2706	(((conduct$3 near5 foil) and resin) and (pattern$5 etch$3)) and (insulat$3 dielectric)	USPAT; US-PGPUB	2003/02/11 12:51
–	2530	((((conduct$3 near5 foil) and resin) and (pattern$5 etch$3)) and (insulat$3 dielectric)) and (via hole recess contact)	USPAT; US-PGPUB	2003/02/11 12:53

-	968	((((((conduct$3 near5 foil) and resin) and (pattern$5 etch$3)) and (insulat$3 dielectric)) and (via hole recess contact)) and (pr resist)	USPAT; US-PGPUB	2003/02/11 12:53
-	755	((((((conduct$3 near5 foil) and resin) and (pattern$5 etch$3)) and (insulat$3 dielectric)) and (via hole recess contact)) and (pr resist)	USPAT	2003/02/11 12:54
-	445	multilayer$3 near3 wir$3 near3 circuit	USPAT; US-PGPUB	2003/02/11 13:02
-	183779	(conduct$3 copper) near5 (foil sheet layer)	USPAT; US-PGPUB	2003/02/11 15:16
-	111368	((conduct$3 copper) near5 (foil sheet layer)) and (etch$3 pattern$4)	USPAT; US-PGPUB	2003/02/11 15:18
-	80228	(((conduct$3 copper) near5 (foil sheet layer)) and (etch$3 pattern$4)) and (via trench hole recess)	USPAT; US-PGPUB	2003/02/11 15:30
-	67836	((((conduct$3 copper) near5 (foil sheet layer)) and (etch$3 pattern$4)) and (via trench hole recess)) and (insulat$3 dielectric)	USPAT; US-PGPUB	2003/02/11 15:31
-	30233	(((((conduct$3 copper) near5 (foil sheet layer)) and (etch$3 pattern$4)) and (via trench hole recess)) and (insulat$3 dielectric)) and (pr photo?resist photoresist resist)	USPAT; US-PGPUB	2003/02/11 15:32
-	28811	((((((conduct$3 copper) near5 (foil sheet layer)) and (etch$3 pattern$4)) and (via trench hole recess)) and (insulat$3 dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu aluminum Al)	USPAT; US-PGPUB	2003/02/11 15:34
-	13674	(((((((conduct$3 copper) near5 (foil sheet layer)) and (etch$3 pattern$4)) and (via trench hole recess)) and (insulat$3 dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu aluminum Al)) and wir$3	USPAT; US-PGPUB	2003/02/11 15:35
-	5322	((((((((conduct$3 copper) near5 (foil sheet layer)) and (etch$3 pattern$4)) and (via trench hole recess)) and (insulat$3 dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu aluminum Al)) and wir$3) and resin	USPAT; US-PGPUB	2003/02/11 15:39
-	834	(((((((((conduct$3 copper) near5 (foil sheet layer)) and (etch$3 pattern$4)) and (via trench hole recess)) and (insulat$3 dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu aluminum Al)) and wir$3) and resin) and (singulat$3 dic$3)	USPAT; US-PGPUB	2003/02/11 16:35
-	4670	((((((((((conduct$3 copper) near5 (foil sheet layer)) and (etch$3 pattern$4)) and (via trench hole recess)) and (insulat$3 dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu aluminum Al)) and wir$3) and resin) and circuit	USPAT; US-PGPUB	2003/02/11 16:36
-	4040	(((((((((((conduct$3 copper) near5 (foil sheet layer)) and (etch$3 pattern$4)) and (via trench hole recess)) and (insulat$3 dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu aluminum Al)) and wir$3) and resin) and circuit) and (cover$3 encapsulat$3)	USPAT; US-PGPUB	2003/02/11 16:37

-	3307	(((((((((((conduct$3 copper) near5 (foil sheet layer)) and (etch$3 pattern$4)) and (via trench hole recess)) and (insulat$3 dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu aluminum Al)) and wir$3) and resin) and circuit) and (cover$3 encapsulat$3)) and ((etch$3 pattern$4) near10 (copper Cu conduct$3))	USPAT; US-PGPUB	2003/02/11 17:36
-	3307	(((((((((((conduct$3 copper) near5 (foil sheet layer)) and (etch$3 pattern$4)) and (via trench hole recess)) and (insulat$3 dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu aluminum Al)) and wir$3) and resin) and circuit) and (cover$3 encapsulat$3)) and ((etch$3 pattern$4) near10 (copper Cu conduct$3))) and wir$3	USPAT; US-PGPUB	2003/02/11 17:36
-	2618	(((((((((((conduct$3 copper) near5 (foil sheet layer)) and (etch$3 pattern$4)) and (via trench hole recess)) and (insulat$3 dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu aluminum Al)) and wir$3) and resin) and circuit) and (cover$3 encapsulat$3)) and ((etch$3 pattern$4) near10 (copper Cu conduct$3))) and wir$3) and bond$3	USPAT; US-PGPUB	2003/02/11 17:39
-	2660	(((((((((((conduct$3 copper) near5 (foil sheet layer)) and (etch$3 pattern$4)) and (via trench hole recess)) and (insulat$3 dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu aluminum Al)) and wir$3) and resin) and circuit) and (cover$3 encapsulat$3)) and ((etch$3 pattern$4) near10 (copper Cu conduct$3))) and wir$3) and (die bond$3)	USPAT; US-PGPUB	2003/02/11 17:42